

SOT1890-1

wafer level chip-scale package; 56 bumps; 0.35 mm pitch, 2.94 mm x 2.59 mm x 0.415 mm body (backside coating included)

1 February 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP56
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	09-08-2016
Manufacturer package code	SOT1890-1

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.91	2.94	2.97	mm
package width	2.56	2.59	2.62	mm
seated height	0.38	0.415	0.45	mm
nominal pitch	-	0.35	-	mm
actual quantity of termination	-	56	-	



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2 Package outline

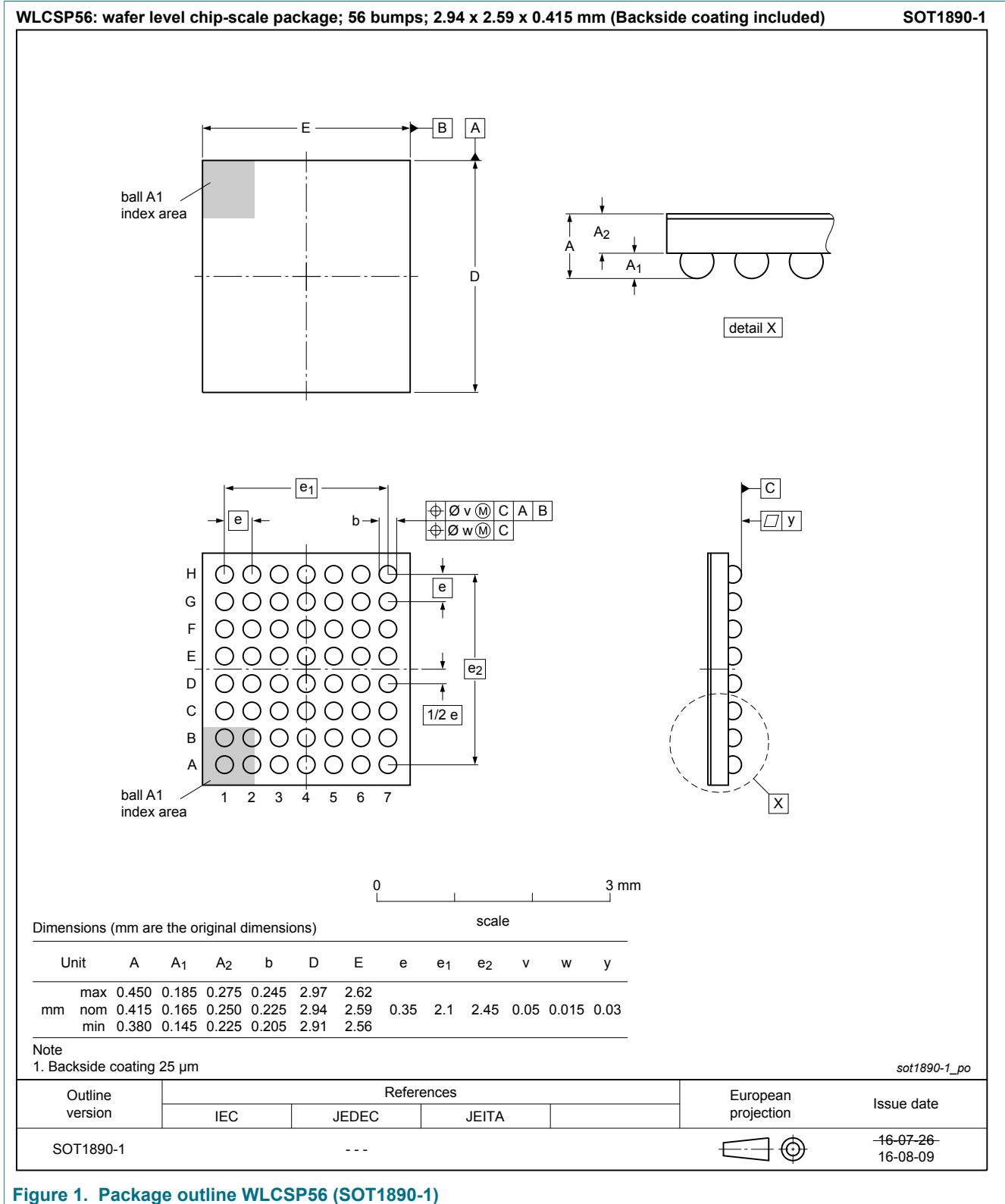


Figure 1. Package outline WLCSP56 (SOT1890-1)

wafer level chip-scale package; 56 bumps; 0.35 mm pitch, 2.94 mm x 2.59 mm x 0.415 mm body
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3 Legal information

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